

#### 150V NPN LED DRIVING TRANSISTOR IN TO252

### **Features**

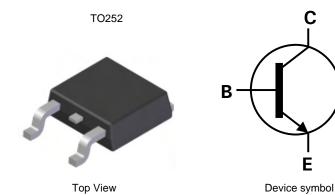
- BV<sub>CEO</sub> > 150V
- $h_{FE} > 100$  for  $I_C = 150mA$ ,  $V_{CE} = 0.25V$
- I<sub>C (cont)</sub> = 1A
- Lead Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Note 2)
- · Qualified to AEC-Q101 Standards for High Reliability

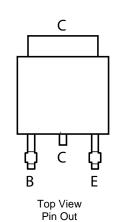
### **Applications**

LED TV backlight

### **Mechanical Data**

- Case: TO252
- Case material: molded Plastic. "Green" molding Compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.34 grams (Approximate)





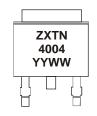
## Ordering Information

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTN4004KTC	ZXTN4004	13	16	2,500

Notes:

- 1. No purposefully added lead.
- 2. "Green" devices, Halogen and Antimony Free, Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

## **Marking Information**



ZXTN4004 = Product Marking Code YYWW = Date Code Marking YY = Last Digit of Year (ex: 10 = 2010) WW = Week Code (01 - 53)



# **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	150	V
Collector-Emitter Voltage	V <sub>CEO</sub>	150	V
Emitter-Base Voltage	$V_{EBO}$	7	V
Continuous Collector Current	Ic	1	A
Peak Pulse Current (Note 4)	I <sub>CM</sub>	3	Α
Base Current	I <sub>B</sub>	500	mA

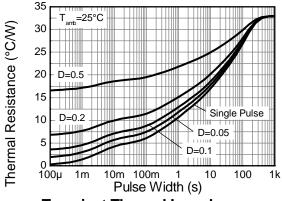
## Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 3)	P <sub>D</sub>	3.8	W
Thermal Resistance, Junction to Ambient	(Note 3)	R <sub>0JA</sub>	33	°C/W
Thermal Resistance, Junction to Leads	(Note 5)	R <sub>0JL</sub>	12	°C/W
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

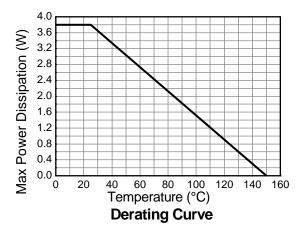
Notes:

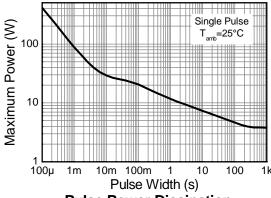
- 3. For a device surface mounted on 50mm X 50mm FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions
- 4. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%.
- 5. Thermal resistance from junction to solder-point (on the exposed collector pad).

## Thermal Characteristics and Derating Information









**Pulse Power Dissipation** 

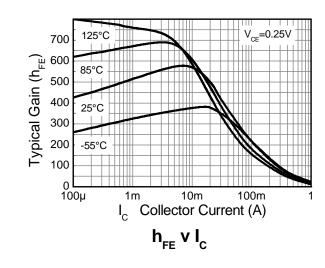


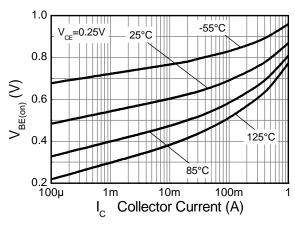
# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

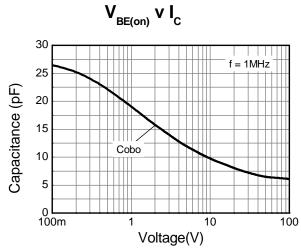
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Emitter Breakdown Voltage (Note 6)	$BV_{CEO}$	150	175	-	V	$I_C = 10mA$
Collector Cut-off Current	I <sub>CBO</sub>	-	-	50	nA	V <sub>CB</sub> = 150V
Emitter Cut-off Current	I <sub>EBO</sub>	-	-	50	nA	$V_{EB} = 7V$
Static Forward Current Transfer Ratio (Note 6)	h <sub>FE</sub>	60	-	-	_	$I_C = 85 \text{mA}, V_{CE} = 0.20 \text{V}$
Static Forward Current Transfer Ratio (Note 0)		100	-	-		$I_C = 150 \text{mA}, V_{CE} = 0.25 \text{V}$
Base-Emitter Turn-On Voltage (Note 6)	$V_{BE(on)}$	-	0.71	0.95	V	$I_C = 150 \text{mA}, V_{CE} = 0.25 \text{V}$
Delay Time	t <sub>(d)</sub>	-	512	-	ns	
Rise Time	t <sub>(r)</sub>	-	426	-	ns	$V_{CC} = 120V, I_C = 150mA,$
Storage Time	t <sub>(S)</sub>	-	3413	-	ns	$-I_{B2} = 1.5 \text{mA}, V_{CE}(ON) = 0.25 \text{V}$
Fall Time	t <sub>(f)</sub>	-	321	-	ns	
Storage Time	t <sub>(S)</sub>	-	65	-	ns	$V_{CC} = 120V, I_{C} = 150mA,$
Fall Time	t <sub>(f)</sub>	-	294	-	ns	$-I_{B2} = 1.5$ mA, $V_{CE}(ON) = 4$ V

Notes: 6. Measured under pulsed conditions. Pulse width =  $300\mu s$ . Duty cycle  $\leq 2\%$ 

## **Typical Characteristics**



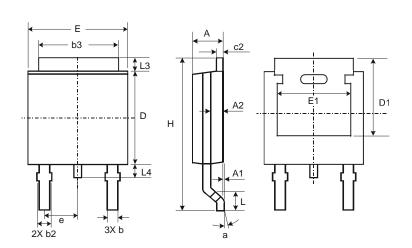




Capacitance v Voltage

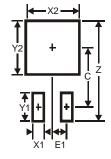


# **Package Outline Dimensions**



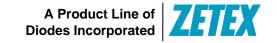
TO252					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
<b>A1</b>	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
q	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
c2	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	_	_		
е	Į.	_	2.286		
Е	6.45	6.70	6.58		
E1	4.32	_	_		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	_		
All Dimensions in mm					

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
С	6.9
F1	2.3





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